**P-Ch MOSFET** 

## **General Description**

The WSD90P06DN56 is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD90P06DN56 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

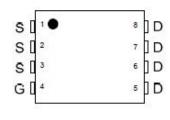
## **Product Summery**

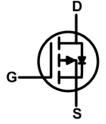
BVDSS	RDSON	ID
-60V	10.5mΩ	-90A

## **Applications**

- Power Management
- Load Switch

# DFN5X6\_8L Pin Configuration





# **Absolute Maximum Ratings**

# DFN5\*6-8L

Symbol	Parameter Rating		Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V -90		Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V -39.7		Α
I <sub>DM</sub>	Pulsed Drain Current -189		А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	96	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range	-55 to 150	${\mathbb C}$

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient		23	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case		1.3	°C/W

**P-Ch MOSFET** 

# P-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-60			V
В	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V , I <sub>D</sub> =-30A		10.5	13.5	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-30A		13.5	17.5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.85	-2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =-32V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
Qg	Total Gate Charge	VDS = -30 V, VGS = -10 V, ID = -17A		121		nC
$Q_{gs}$	Gate-Source Charge			20		
$Q_gd$	Gate-Drain Charge			32		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = -30 \text{ V}, \text{ RL} = 30\Omega$ $I_{D} = -1 \text{ A}, \text{ VGEN} = -10 \text{ V}, \text{ Rg} = 6$		20		
Tr	Rise Time			20		no
T <sub>d(off)</sub>	Turn-Off Delay Time			205		ns
T <sub>f</sub>	Fall Time			90		
C <sub>iss</sub>	Input Capacitance	VDS=-30V,VGS=0V, f=1.0MHz		5600		
Coss	Output Capacitance			510		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			480		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	T <sub>C</sub> =25 °C			-64	Α
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1.2	V

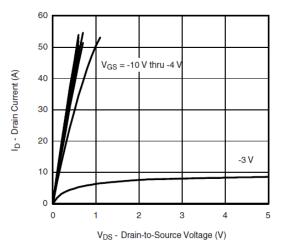
A: The value of Regain measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with Ta=25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

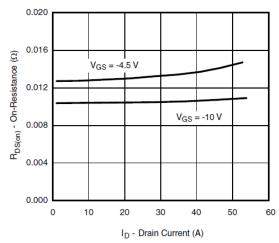
C: The current rating is based on the t≤ 10s junction to ambient thermal resistance rating.



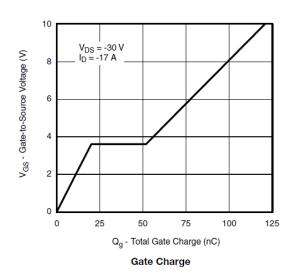
# **P-Channel Typical Characteristics**

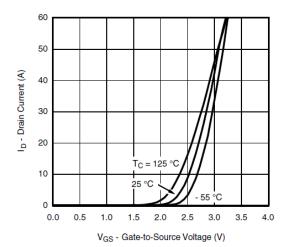


#### **Output Characteristics**

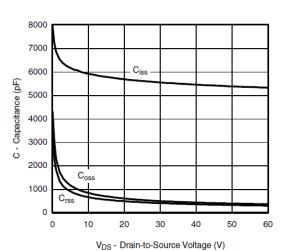


On-Resistance vs. Drain Current

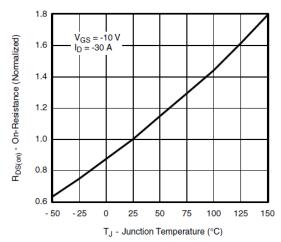




Transfer Characteristics

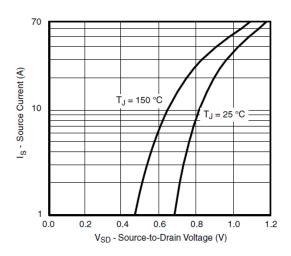


Capacitance

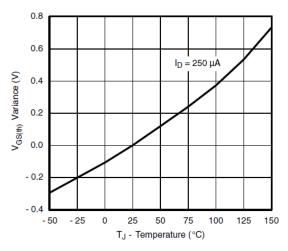


On-Resistance vs. Junction Temperature

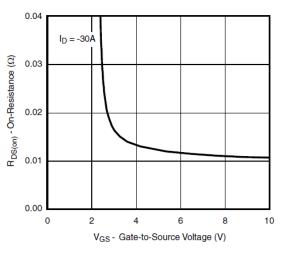




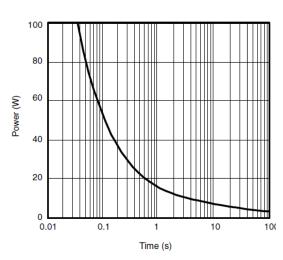
Source-Drain Diode Forward Voltage



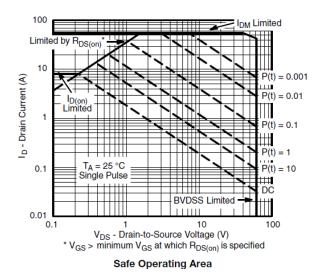
Threshold Voltage



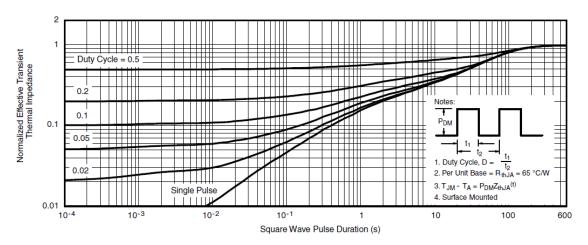
On-Resistance vs. Gate-to-Source Voltage



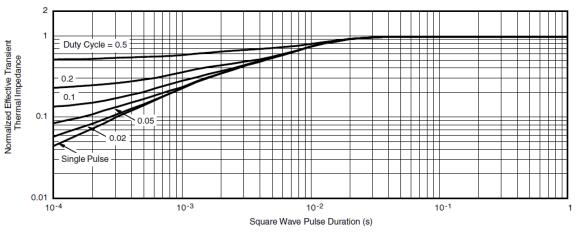
Single Pulse Power, Junction-to-Ambient







Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case



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